DS36C278

DS36C278 Low Power Multipoint EIA-RS-485 Transceiver



Literature Number: SNLS096B



DS36C278

Low Power Multipoint EIA-RS-485 Transceiver

General Description

The DS36C278 is a low power differential bus/line transceiver designed to meet the requirements of RS-485 standard for multipoint data transmission. In addition it is compatible with TIA/EIA-422-B.

The CMOS design offers significant power savings over its bipolar and ALS counterparts without sacrificing ruggedness against ESD damage. The device is ideal for use in battery powered or power conscious applications. $I_{\rm CC}$ is specified at 500 μA maximum.

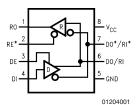
The driver and receiver outputs feature TRI-STATE® capability. The driver outputs operate over the entire common mode range of -7V to +12V. Bus contention or fault situations that cause excessive power dissipation within the device are handled by a thermal shutdown circuit, which forces the driver outputs into the high impedance state.

The receiver incorporates a fail safe circuit which guarantees a high output state when the inputs are left open. (Note 1) The DS36C278T is fully specified over the industrial temperature range $(-40^{\circ}\text{C to} + 85^{\circ}\text{C})$.

Features

- 100% RS-485 compliant
 - Guaranteed RS-485 device interoperation
- Low power CMOS design: I_{CC} 500 µA max
- Built-in power up/down glitch-free circuitry
 - Permits live transceiver insertion/displacement
- DIP and SOIC packages available
- Industrial temperature range: -40°C to +85°C
- On-board thermal shutdown circuitry
 - Prevents damage to the device in the event of excessive power dissipation
- Wide common mode range: -7V to +12V
- Receiver open input fail-safe (Note 1)
- 1/4 unit load (DS36C278): ≥128 nodes
- ½ unit load (DS36C278T): ≥64 nodes
- ESD (human body model): ≥2 kV
- Drop in replacement for:
 - LTC485, MAX485, DS75176, DS3695

Connection Diagram



Order Number DS36C278TM, DS36C278TN, DS36C278M, DS36C278N See NS Package Number M08A or N08E

Truth Table

DRIVER SECTION							
RE*	DE	DI	DO/RI	DO*/RI*			
Х	Н	Н	Н	L			
X	Н	L	L	Н			
Х	L	Х	Z	Z			
RECEIVE	RECEIVER SECTION						
RE*	DE	В	I-RI*	RO			
	DE	п	u-nı	no			
L	L		+0.2V	Н			
L	L L	≥-					
L L H	L L L	≥-	+0.2V				

Note 1: Non-terminated, open input only

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Absolute Maximum Ratings (Note 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V_{CC}) +12V Input Voltage (DE, RE*, & DI) -0.5V to (V_{CC} +0.5V) Common Mode (V_{CM})

Driver Output/Receiver Input ± 15 V Input Voltage (DO/RI, DO*/RI*) ± 14 V Receiver Output Voltage -0.5V to (V_{CC} +0.5V)

Maximum Package Power Dissipation

@ +25°C

M Package 1190 mW, derate 9.5 mW/°C above

+25°C

N Package 744 mW, derate 6.0 mW/°C above

+25°C

Storage Temperature Range -65°C to +150°C

Lead Temperature
(Soldering 4 sec) +260°C

Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage (V _{CC})	+4.75	+5.0	+5.25	V
Bus Voltage	-7		+12	V
Operating Free Air Temp	oerature ((Ta)		
DS36C278T	-40	25	+85	°C
DS36C278	0	25	+70	°C

Electrical Characteristics (Notes 3, 4)

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified

	Conditio	115	Re	ference	Min	Тур	Max	Units
ENTIAL DRIVER CHARACTE	RISTICS							
Differential Output Voltage	I _O = 0 mA (No Load)		(400)		1.5		5.0	V
Output Voltage	$I_O = 0 \text{ mA}$		l .	. ,	0		5.0	V
Output Voltage	(Output to GND)		(485)		0		5.0	V
Differential Output Voltage	$R_L = 50\Omega$		(422)	Figure 1	2.0	2.8		V
(Termination Load)	$R_L = 27\Omega$		(485)		1.5	2.3	5.0	V
Balance of V _{OD2}	$R_L = 27\Omega \text{ or } 50\Omega$		(N	lote 5)	-0.2	0.1	+0.2	V
$ V_{OD2} - V_{0D2^*} $			(42	2, 485)				
Differential Output Voltage	R1 = 54Ω , R2 = 375Ω	2	Figure 2		1.5	2.0	F 0	V
(Full Load)	$V_{TEST} = -7V \text{ to } +12V$				1.5	2.0	5.0	V
Driver Common Mode	$R_L = 27\Omega$		(485)	Figure 1	0		3.0	V
Output Voltage	$R_L = 50\Omega$		(422)	rigure i	0		3.0	V
Balance of V _{OC}	$R_L = 27\Omega$ or		(N	(Note 5)			10.2	V
IV _{OC} - V _{OC*} I	$R_L = 50\Omega$		(422, 485)		-0.2		+0.2	v
Driver Output Short-Circuit	V _O = +12V		(485)	Figure 4		200	+250	mA
Current	$V_O = -7V$		(485)			-190	-250	mA
ER CHARACTERISTICS								
Differential Input High	$V_{\rm O} = V_{\rm OH}, I_{\rm O} = -0.4 V$					10.035	10.2	V
Threshold Voltage	$-7V \le V_{CM} \le +12V$		(N	lote 6)		+0.033	+0.2	V
Differential Input Low	$V_{\rm O} = V_{\rm OL}, I_{\rm O} = 0.4 \text{ m/s}$	A	(422, 485)		_0.2	_0.035		V
Threshold Voltage	$-7V \le V_{CM} \le +12V$				-0.2	-0.003		v
Hysteresis	$V_{CM} = 0V$	(Note 7)		lote 7)		70		mV
Input Resistance	$-7V \le V_{CM} \le +12V$		DS3	86C278T	24	68		kΩ
Input Resistance	$-7V \le V_{CM} \le +12V$		DS36C278		48	68		kΩ
Line Input Current	Other Input = 0V,	DS36C278	V _{IN}	= +12V	0	0.19	0.25	mA
(Note 8)	$DE = V_{IL}, RE^* = V_{IL},$		VIN	$_{1} = -7V$	0	-0.1	-0.2	mA
	V_{CC} = 4.75 to 5.25	DS36C278T	V _{IN}	= +12V	0	0.19	0.5	mA
	or 0V		VIN	₁ = -7V	0	-0.1	-0.4	mA
Line Input Current Glitch	Other Input = 0V,	DS36C278	V _{IN}	= +12V	0	0.19	0.25	mA
(Note 8)	$DE = V_{IL}, RE^* = V_{IL},$		VIN	_I = -7V	0	-0.1	-0.2	mA
	$V_{CC} = +3.0V \text{ or } 0V,$	DS36C278T	V _{IN}	= +12V	0	0.19	0.5	mA
	$T_A = 25^{\circ}C$		V _{IN}	_I = -7V	0	-0.1	-0.4	mA
	Differential Output Voltage Output Voltage Output Voltage Differential Output Voltage (Termination Load) Balance of V _{OD2} IV _{OD2} - V _{OD2*} I Differential Output Voltage (Full Load) Driver Common Mode Output Voltage Balance of V _{OC} IV _{OC} - V _{OC*} I Driver Output Short-Circuit Current ER CHARACTERISTICS Differential Input High Threshold Voltage Differential Input Low Threshold Voltage Hysteresis Input Resistance Input Resistance Line Input Current (Note 8)	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$

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Electrical Characteristics (Notes 3, 4) (Continued)
Over Supply Voltage and Operating Temperature ranges, unless otherwise specified

Symbol	Parameter	Conditions		Reference	Min	Тур	Max	Units
RECEIVER CHARACTERISTICS								
I _B	Input Balance Test	$RS = 500\Omega$		(422) (Note 10)			±400	mV
V _{OH}	High Level Output Voltage	$I_{OH} = -4 \text{ mA}, V_{ID} = +0.$.2V	RO	3.5	4.6		V
V _{OL}	Low Level Output Voltage	$I_{OL} = +4 \text{ mA}, V_{ID} = -0.$	2V	Figure 11		0.3	0.5	V
I _{OSR}	Short Circuit Current	V _O = GND		RO	7	35	85	mA
I _{OZR}	TRI-STATE Leakage Current	V _O = 0.4V to 2.4V		nO			±1	μA
DEVICE	CHARACTERISTICS						•	
V _{IH}	High Level Input Voltage				2.0		V _{CC}	V
V _{IL}	Low Level Input Voltage			DE,	GND		0.8	V
I _{IH}	High Level Input Current	$V_{IH} = V_{CC}$		RE*,			2	μA
I _{IL}	Low Level Input Current	$V_{CC} = 5V$	V _{II} = 0V	DI			-2	μA
		$V_{CC} = +3.0V$	V _{IL} = UV				-2	μA
I _{cc}	Power Supply Current	Driver and Receiver Of	V			200	500	μA
I _{CCR}	(No Load)	Driver OFF, Receiver ON		.,		200	500	μA
I _{CCD}		Driver ON, Receiver OFF		V _{cc}		200	500	μA
I _{ccz}		Driver and Receiver Of	FF .			200	500	μΑ

Switching Characteristics (Notes 4, 9)

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified

Symbol	Parameter	Conditions	Conditions Reference		Min Typ		Units
DRIVER CHARACTERISTICS							
t _{PHLD}	Differential Propagation	$R_L = 54\Omega, C_L = 100 pF$		10	39	80	ns
	Delay High to Low			10	39	80	115
t _{PLHD}	Differential Propagation			10	40	80	ns
	Delay Low to High		Figures F 6	10	40	00	115
t _{SKD}	Differential Skew		Figures 5, 6	0	1	10	ns
	lt _{PHLD} – t _{PLHD} l			U	'	10	115
t _r	Rise Time			3	25	50	ns
t _f	Fall Time			3	25	50	ns
t _{PHZ}	Disable Time High to Z	C _L = 15 pF	Figures 7, 8	_	80	200	ns
t _{PLZ}	Disable Time Low to Z	RE * = L	Figures 9, 10	_	80	200	ns
t _{PZH}	Enable Time Z to High	C _L = 100 pF	Figures 7, 8	_	50	200	ns
t _{PZL}	Enable Time Z to Low	RE * = L	Figures 9, 10	_	65	200	ns
RECEIVER	CHARACTERISTICS	,			•	•	
t _{PHL}	Propagation Delay	C _L = 15 pF		30	010	400	
	High to Low			30	210	400	ns
t _{PLH}	Propagation Delay		Figures 12, 13	30	190	400	no
	Low to High			30	190	400	ns
t _{SK}	Skew, It _{PHL} - t _{PLH} I			0	20	50	ns
t _{PLZ}	Output Disable Time	C _L = 15 pF		_	50	150	ns
t _{PHZ}			Figure 14 15 10	_	55	150	ns
t _{PZL}	Output Enable Time		Figures 14, 15, 16	_	40	150	ns
t _{PZH}				_	45	150	ns

Switching Characteristics (Notes 4, 9) (Continued)

Note 2: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" specifies conditions of device operation.

Note 3: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except V_{OD1} and V_{OD2} .

Note 4: All typicals are given for: $V_{CC} = +5.0V$, $T_A = +25^{\circ}C$.

 $\textbf{Note 5:} \ \ \text{Delta} \ \ |V_{OD2}| \ \ \text{and} \ \ V_{OC}, \ \text{respectively, that occur when input changes state}.$

Note 6: Threshold parameter limits specified as an algebraic value rather than by magnitude.

Note 7: Hysteresis defined as $V_{HST} = V_{TH} - V_{TL}$.

Note 8: I_{IN} includes the receiver input current and driver TRI-STATE leakage current.

Note 9: C_L includes probe and jig capacitance.

Note 10: For complete details of test, see RS-485.

Parameter Measurement Information

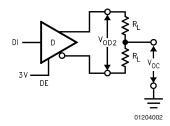


FIGURE 1. Driver $V_{\rm OD2}$ and $V_{\rm OC}$

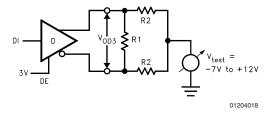


FIGURE 2. Driver V_{OD3}

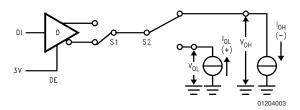
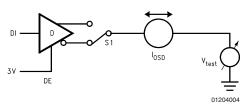


FIGURE 3. Driver $\rm V_{OH}$ and $\rm V_{OL}$



Vtest = -7V to +12V

FIGURE 4. Driver I_{OSD}

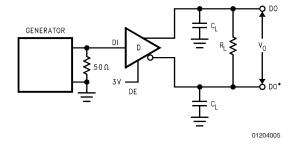


FIGURE 5. Driver Differential Propagation Delay Test Circuit

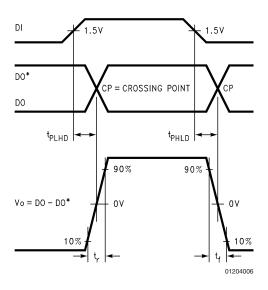


FIGURE 6. Driver Differential Propagation Delays and Differential Rise and Fall Times

Parameter Measurement Information (Continued)

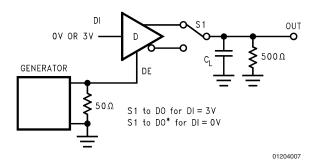


FIGURE 7. TRI-STATE Test Circuit (t_{PZH} , t_{PHZ})

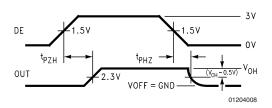


FIGURE 8. TRI-STATE Waveforms (t_{PZH} , t_{PHZ})

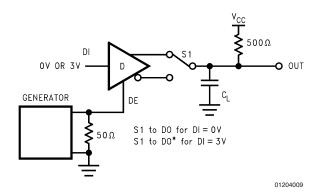


FIGURE 9. TRI-STATE Test Circuit (t_{PZL} , t_{PLZ})

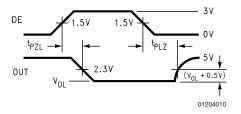


FIGURE 10. TRI-STATE Waveforms (t_{PZL} , t_{PLZ})

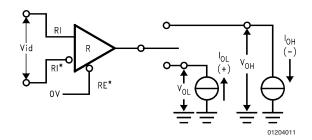


FIGURE 11. Receiver $\rm V_{OH}$ and $\rm V_{OL}$

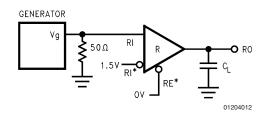


FIGURE 12. Receiver Differential Propagation Delay Test Circuit

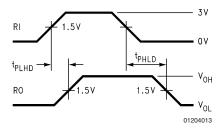


FIGURE 13. Receiver Differential Propagation Delay Waveforms

Parameter Measurement Information (Continued)

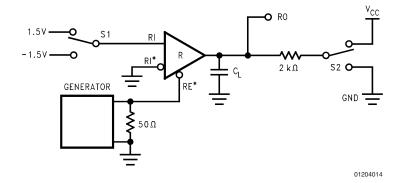


FIGURE 14. Receiver TRI-STATE Test Circuit

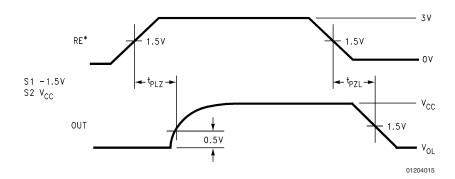


FIGURE 15. Receiver Enable and Disable Waveforms ($t_{\text{PLZ}},\,t_{\text{PZL}}$)

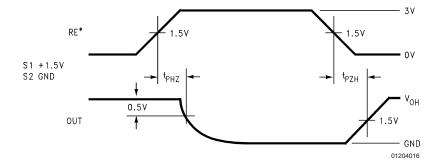


FIGURE 16. Receiver Enable and Disable Waveforms ($t_{\text{PHZ}},\,t_{\text{PZH}}$)

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Typical Application Information

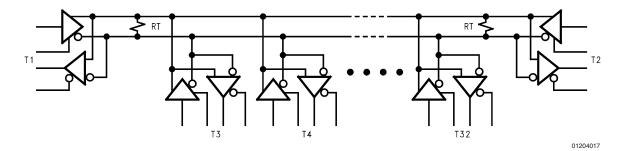


FIGURE 17. Typical RS-485 Bus Interface

TABLE 1. Device Pin Descriptions

Pin	Name	Description
No.		
1	RO	Receiver Output: When RE (Receiver Enable) is LOW, the receiver is enabled (ON), if DO/RI ≥ DO*/RI*
		by 200 mV, RO will be HIGH. If DO/RI ≤ DO*/RI* by 200 mV, RO will be LOW. Additionally RO will be
		HIGH for OPEN (Non-terminated) Inputs.
2	RE*	Receiver Output Enable: When RE* is LOW the receiver output is enabled. When RE* is HIGH, the
		receiver output is in TRI-STATE (OFF).
3	DE	Driver Output Enable: When DE is HIGH, the driver outputs are enabled. When DE is LOW, the driver
		outputs are in TRI-STATE (OFF).
4	DI	Driver Input: When DE (Driver Enable) is HIGH, the driver is enabled, if DI is LOW, then DO/RI will be
		LOW and DO*/RI* will be HIGH. If DI is HIGH, then DO/RI is HIGH and DO*/RI* is LOW.
5	GND	Ground Connection.
6	DO/RI	Driver Output/Receiver Input, 485 Bus Pin.
7	DO*/RI*	Driver Output/Receiver Input, 485 Bus Pin.
8	V _{cc}	Positive Power Supply Connection: Recommended operating range for V _{CC} is +4.75V to +5.25V.

Unit Load

A unit load for an RS-485 receiver is defined by the input current versus the input voltage curve. The gray shaded region is the defined operating range from -7V to +12V. The top border extending from -3V at 0 mA to +12V at +1 mA is defined as one unit load. Likewise, the bottom border extending from +5V at 0 mA to -7V at -0.8 mA is also defined as one unit load (see Figure 18). An RS-485 driver is capable of driving up to 32 unit loads. This allows up to 32 nodes on a single bus. Although sufficient for many applications, it is sometimes desirable to have even more nodes. For example, an aircraft that has 32 rows with 4 seats per row would benefit from having 128 nodes on one bus. This would allow signals to be transferred to and from each individual seat to 1 main station. Usually there is one or two less seats in the last row of the aircraft near the restrooms and food storage area. This frees the node for the main

The DS36C278, the DS36C279, and the DS36C280 all have $\frac{1}{2}$ unit load and $\frac{1}{4}$ unit load (UL) options available. These devices will allow up to 64 nodes or 128 nodes guaranteed over temperature depending upon which option is selected. The $\frac{1}{2}$ UL option is available in industrial temperature and the $\frac{1}{4}$ UL is available in commercial temperature.

First, for a $\frac{1}{2}$ UL device the top and bottom borders shown in Figure 18 are scaled. Both 0 mA reference points at +5V and -3V stay the same. The other reference points are +12V at +0.5 mA for the top border and -7V at -0.4 mA for the bottom border (see Figure 18). Second, for a $\frac{1}{4}$ UL device the top and bottom borders shown in Figure 18 are scaled also. Again, both 0 mA reference points at +5V and -3V stay the same. The other reference points are +12V at +0.25 mA for the top border and -7V at -0.2 mA for the bottom border (see Figure 18).

The advantage of the $\frac{1}{2}$ UL and $\frac{1}{4}$ UL devices is the increased number of nodes on one bus. In a single master multi-slave type of application where the number of slaves exceeds 32, the DS36C278/279/280 may save in the cost of extra devices like repeaters, extra media like cable, and/or extra components like resistors.

The DS36C279 and DS36C280 have an additional feature which offers more advantages. The DS36C279 has an automatic sleep mode function for power conscious applications. The DS36C280 has a slew rate control for EMI conscious applications. Refer to the sleep mode and slew rate control portion of the application information section in the corresponding datasheet for more information on these features.

Unit Load (Continued)

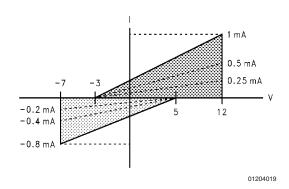
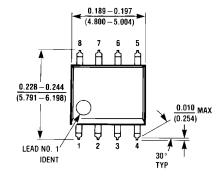
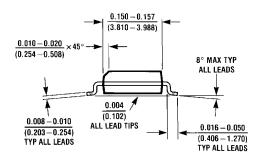


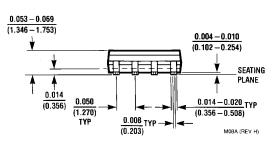
FIGURE 18. Input Current vs Input Voltage Operating Range

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Physical Dimensions inches (millimeters) unless otherwise noted

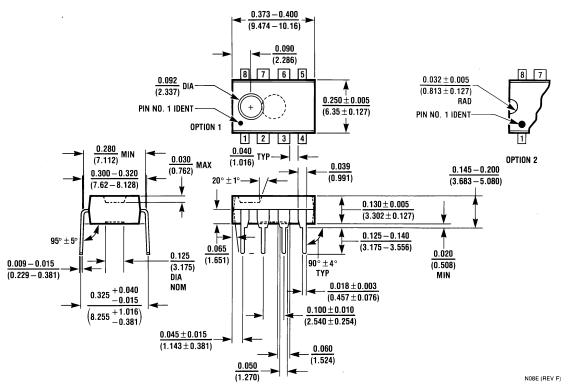






8-Lead (0.150" Wide) Molded Small Outline Package, JEDEC Order Number DS36C278TM, DS36C278M **NS Package Number M08A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



8-Lead (0.300" Wide) Molded Dual-In-Line Package Order Number DS36C278TN, DS36C278N **NS Package Number N08E**

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